

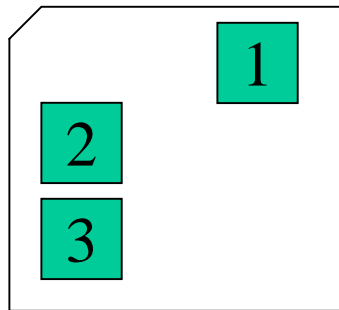
X-Ray of Alenia Parts

M. Gilchriese

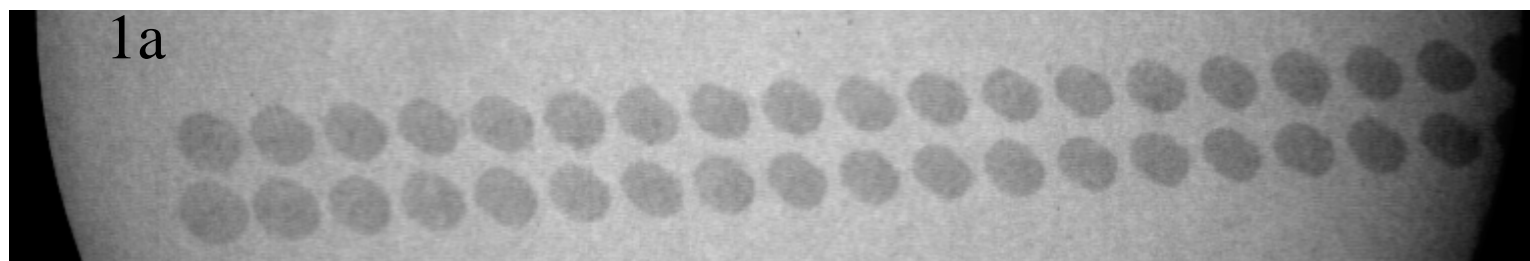
May 1999

Method

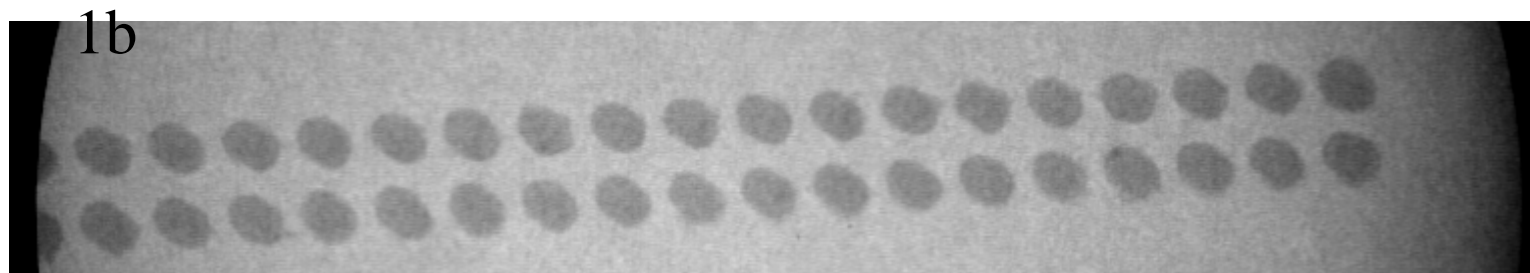
- X-Ray of modules and single chip assemblies at X-Tek
- All done in GELpaks. Chip number as below.



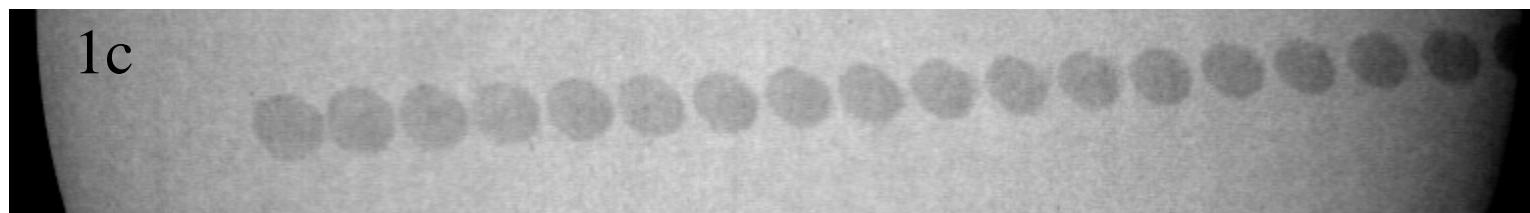
Chip 1



Near row 0
Close to merge



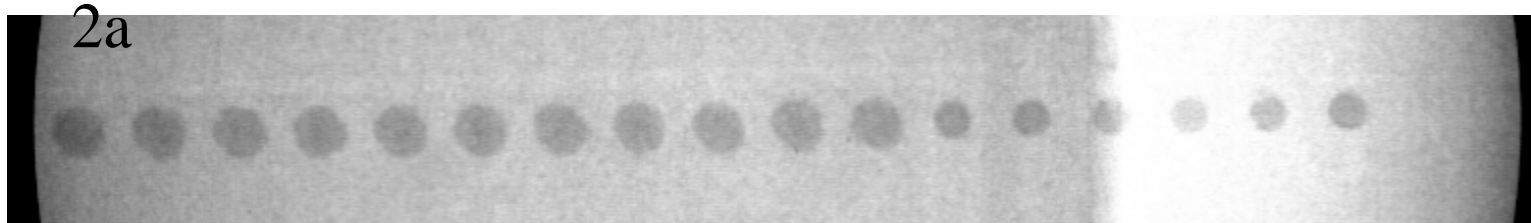
Same column
as above but
near row 160



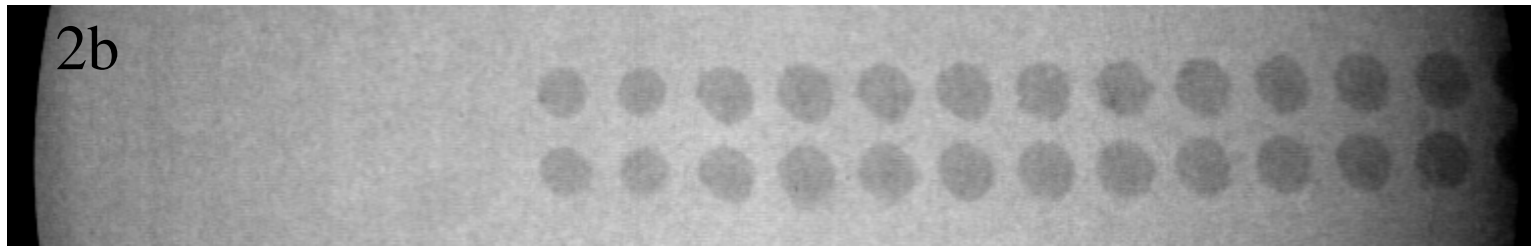
Row 0 near
edge, col. 17
Worst area
for possible
merged bumps

Missing: 0 Merged: 0 but close, see above

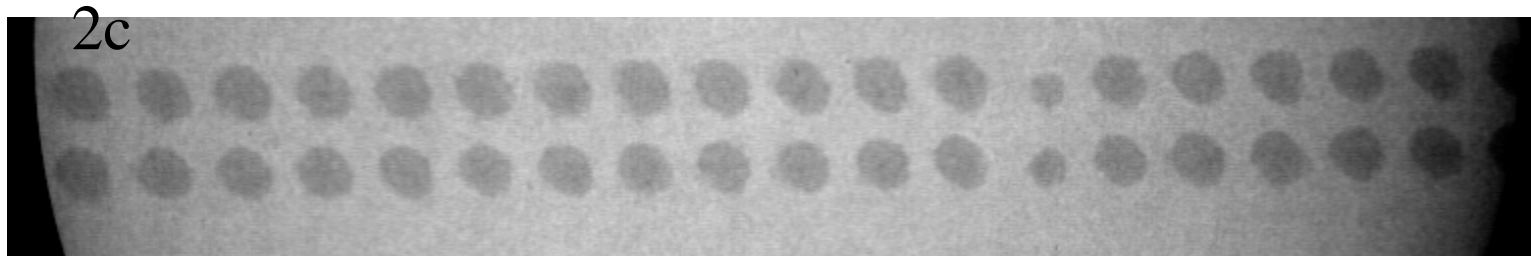
Chip 2



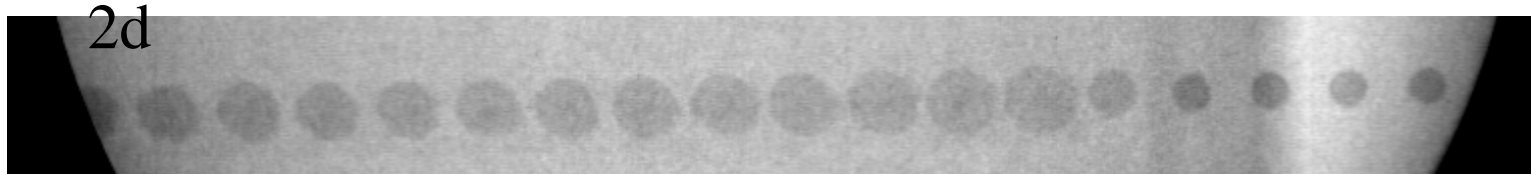
Col. 0 near
row 160. Is
this misplaced
or feature of
this detector?



Col. 1-2 near
row 0.



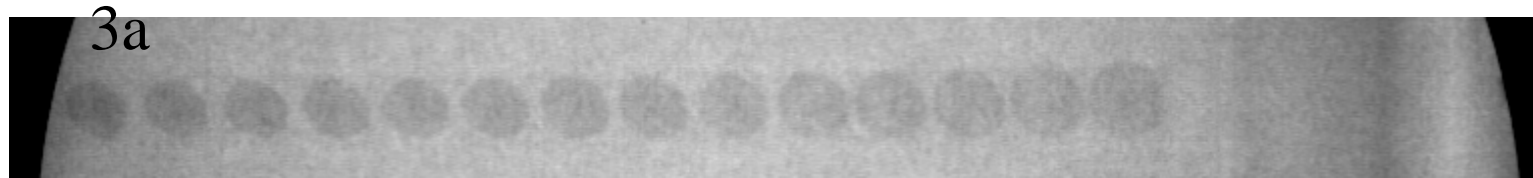
Col. 12-13 near
row 0. 2 missing
bumps



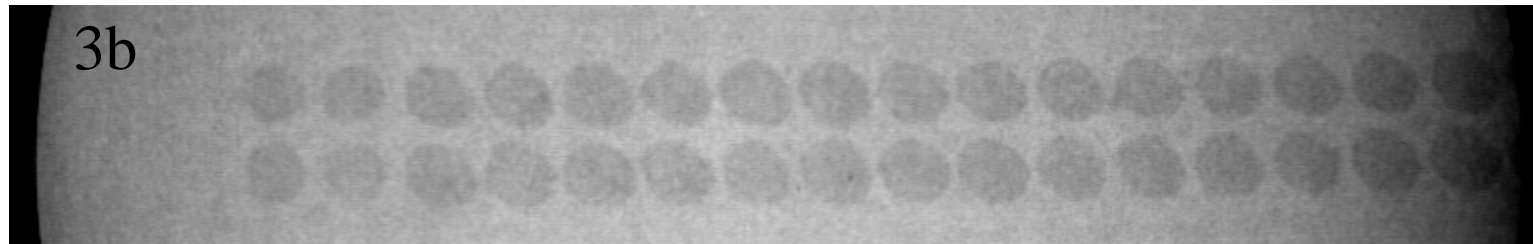
Col. 17 near
row 160.
Edge problem
of near merge

Missing: 2 Merge: 0, but close at edge as above

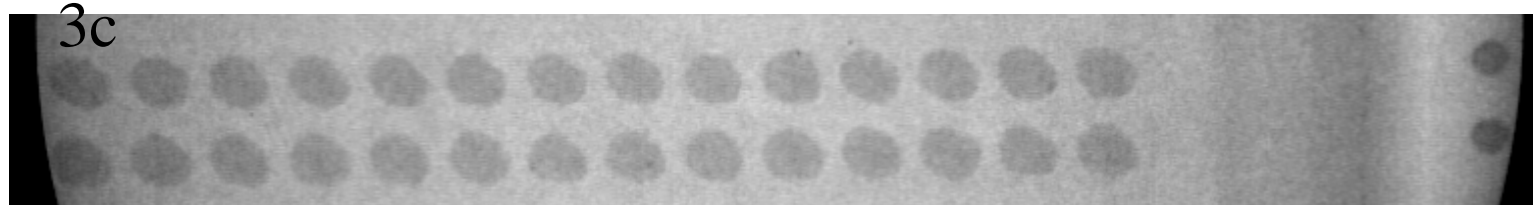
Chip 3



Col.0, near row
160, edge
problem



Col.15-16, near
row 0, close
to merged



Col.15-16, near
row 160



Col.17, near
row 0, likely
merged



Col.17, near
row 160

Missing:0

Merged: Not clear, possibly 10 or so